Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-24. (Canceled).

(New) A flexible printed wiring board comprising:

a metal film before patterning,

a resin coating on said metal film,

an opening formed in said resin coating, and

a metal bump located in said opening, connected at its bottom face to said metal film and having a height greater than the thickness of said resin coating,

wherein said resin coating is removed at the portion located at a top face of said metal bump and the top face of said metal bump is exposed from the surface of said resin coating.

2. 26. (New) The flexible printed wiring board according to claim 25,

wherein said resin coating have a first resin coating made of rigid resin close contacted to said metal film, and a second resin coating having adhesive close contacted to said first resin coating.

3. 27. (New) A flexible printed wiring board comprising:

a metal film,

a resin coating on said metal film,

an opening formed in said resin coating, and

a metal bump located in said opening, connected at its bottom face to said metal film and having a height greater than the thickness of said resin coating,

Application No. 09/909,827

wherein said resin coating is removed at the portion located at a top face of said metal bump and the top face of said metal bump is exposed from the surface of said resin coating,

wherein said resin coating have a first resin coating made of rigid resin close contacted to said metal film, and a second resin coating having adhesive close contacted to said first resin coating, and said second resin coating is exposed.

4. 28. (New) The flexible printed wiring board according to claim 27 wherein said metal film is patterned in a predetermined form.

5. 29. (New) The flexible printed wiring board according to claim 28, wherein an electric device is mounted on said flexible printed wiring board and a bonding pad of said electric device is connected with the front face of said metal bump.